

L Number	Hits	Search Text	DB	Time stamp
1	39	((smart near5 cut) (substrate near3 bond\$3)) and (separat\$3 near5 (film layer))) and (implant\$3 dop\$4)	EPO; JPO; DERWENT; IBM_TDB	2004/08/19 10:45
3	32	(((((substrate near3 bond\$3)) and (separat\$3 near5 (film layer))) and (pressure near5 (fluid gas air))) and (chip die dice)) and (implant\$3 dop\$4)) and (remov\$3 same separat\$3 same chip)	USPAT; US-PGPUB	2004/08/19 11:49
4	208866	pressure near5 fluid	USPAT; US-PGPUB	2004/08/19 14:05
5	21181	(pressure near5 fluid) and ((pressure near5 (fluid gas air)) and (chip die dice))	USPAT; US-PGPUB	2004/08/19 14:05
6	3461	((pressure near5 fluid) and ((pressure near5 (fluid gas air)) and (chip die dice))) and semiconductor	USPAT; US-PGPUB	2004/08/19 14:05
7	35	((pressure near5 fluid) and ((pressure near5 (fluid gas air)) and (chip die dice))) and semiconductor) and kerf	USPAT; US-PGPUB	2004/08/19 12:20
8	3461	((pressure near5 fluid) and ((pressure near5 (fluid gas air)) and (chip die dice))) and semiconductor) and (chip die dice)	USPAT; US-PGPUB	2004/08/19 12:21
9	1981	((pressure near5 fluid) and ((pressure near5 (fluid gas air)) and (chip die dice))) and semiconductor) and (chip die dice)	USPAT; US-PGPUB	2004/08/19 14:05
19	105535	and bond\$3 pressure near5 fluid	EPO; JPO; DERWENT; IBM_TDB	2004/08/19 14:05
20	2304	(pressure near5 fluid) and ((pressure near5 (fluid gas air)) and (chip die dice))	EPO; JPO; DERWENT; IBM_TDB	2004/08/19 14:05
21	0	((pressure near5 fluid) and ((pressure near5 (fluid gas air)) and (chip die dice))) and semiconductor	USPAT; US-PGPUB	2004/08/19 14:05
22	155	((pressure near5 fluid) and ((pressure near5 (fluid gas air)) and (chip die dice))) and semiconductor	EPO; JPO; DERWENT; IBM_TDB	2004/08/19 14:05
23	29	((pressure near5 fluid) and ((pressure near5 (fluid gas air)) and (chip die dice))) and semiconductor) and bond\$3	EPO; JPO; DERWENT; IBM_TDB	2004/08/19 14:06